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(54) Title: A METHOD FOR FORMING METAL CAPPED SUBSTRATE IMPRINTS

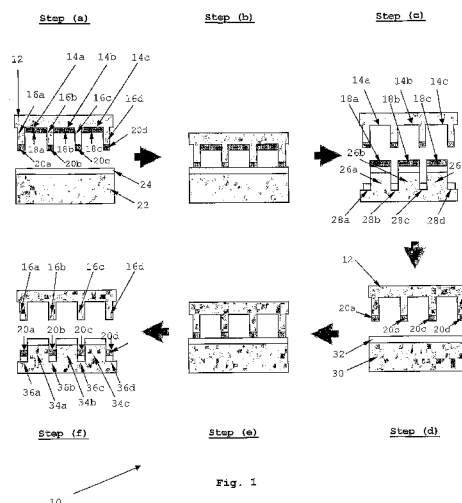


Fig. 1

(57) Abstract: A method for selectively depositing a metal layer on a substrate is provided. The method comprises the steps of: (a) providing a mold having an imprint forming surface coated with said metal layer thereon, wherein said imprint forming surface comprises a first region and a second region, and wherein said first region is dimensioned to have a greater surface area compared to said second region; and (b) contacting said mold to said substrate to form an imprint on said substrate and to simultaneously selectively deposit said metal layer from said first region of said mold to said imprint on said substrate.